Development

Printed Electronics Materials Copper oxide paste for photo sintering

Curelight[®]

Curelight[®] can be formed on low heat resistant substrates

Features

- Rapid sintering under the air atmosphere
- Low volume resistivity
- **Fine line printing** \checkmark
- \checkmark Good adhesion on substrate
- Long shelf life



RFID tag formed by Photo sintering

Photo sintering Process

- Formed on low heat resistant substrates
- **High productivity**
- **Space saving**

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Printing	Drying	Photo sintering	Conductor formation

Application

RFID Antenna, electromagnetic wave shield, Sensor, Touch panel, FPC etc.

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Properties of <i>Curelight</i> ®		
Conductive particle	Copper oxide (Cu2O)	
Cu2O Content	40 – 80 wt.%	
Solvent	Organic Solvent	
Particle size	100 - 200 nm	

Properties of photo sintering Cu film (After press)

Volume resistivity	< 20 μΩ ・ cm
Film thickness	< 10 μm
Applicable substrate	PET, Paper, PI
Adhesive tape peel test	Pass